

## **Amendments to the Specification**

**Please amend the heading on page 1, line 1 as follows:**

~~DESCRIPTION~~

**Please insert the following heading on page, before line 4:**

**BACKGROUND OF THE INVENTION**

**Please amend the sub-heading on line 5 of page 1 as follows:**

**1. Technical Field TECHNICAL FIELD**

**Please amend the sub-heading on line 11 of page 1 as follows:**

**2. Description of Related Art BACKGROUND ART**

**Please amend the paragraph beginning on page 1, line 12 as follows:**

Substrate processing apparatuses such as for example semiconductor manufacturing apparatuses that perform prescribed processing of semiconductor substrates (wafers) and LCD (Liquid Crystal Display) manufacturing apparatuses that perform prescribed processing of glass substrates for LCDs, are provided with a plurality of process chambers, in each of ~~which the~~ process chambers a substrate process such as film formation is carried out. Also, transfer machines are used to convey substrates between process chambers.

**Please amend the paragraph (four lines) beginning on page 1, line 27 as follows:**

~~Patent Document 1~~

The following documents disclose related apparatuses:

Unexamined Patent Application Publication No. Hei 11-102953; and

~~Patent Document 2~~

Unexamined Patent Application Publication No. Hei 10-199960.

**Please amend the heading on line 3 of page 2 as follows:**

**DISCLOSURE SUMMARY OF THE INVENTION**

**Please amend the heading on line 19 of page 5 as follows:**

**BRIEF DESCRIPTION OF THE DRAWINGS**

**Please amend the heading on line 3 of page 2 as follows:**

**BEST MODE FOR CARRYING OUT DETAILED DESCRIPTION OF THE INVENTION**